

### 描述 / Descriptions

SOT-89 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-89 Plastic Package.

### 特征 / Features

饱和压降低,与 2SB1132 互补。

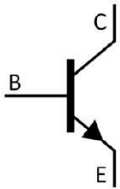
Low saturation voltage, complements the 2SB1132.

### 用途 / Applications

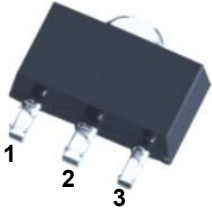
用于中功率放大。

Medium power amplifier applications.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN 1 : Base      PIN 2 : Collector      PIN 3 : Emitter

### 印章代码 / Marking

$h_{FE}$ Classifications Symbol	P	Q	R
$h_{FE}$ Range	82~180	120~270	180~390
Marking	HDAP*	HDAQ*	HDAR*

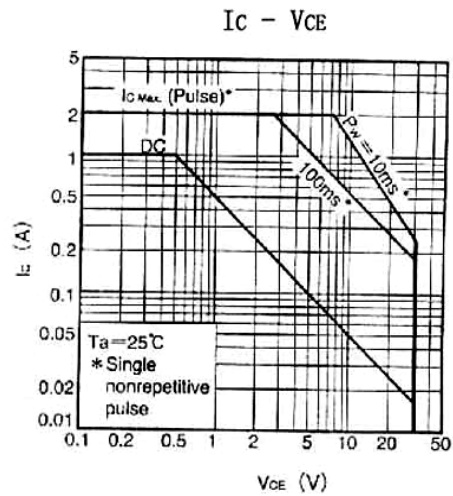
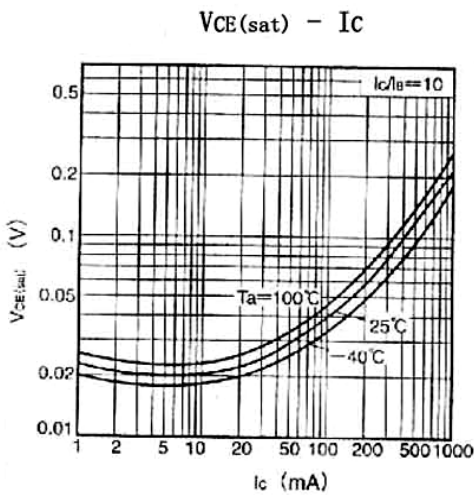
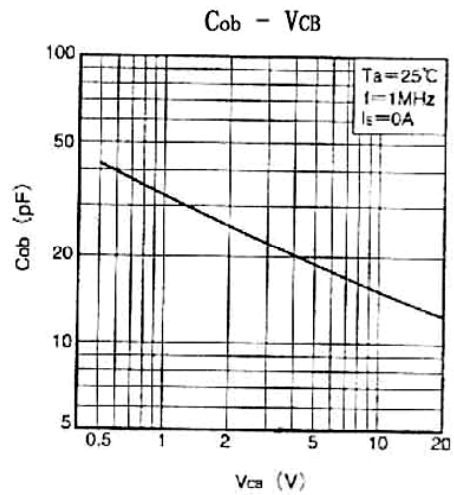
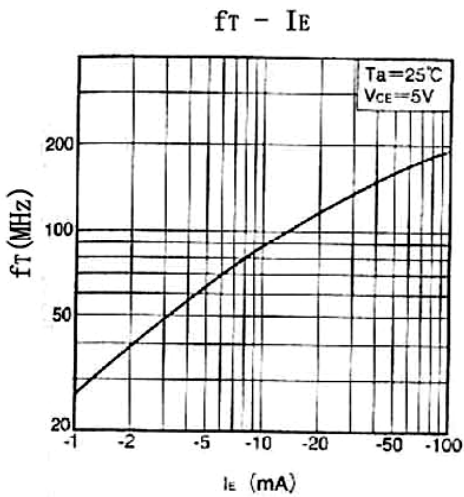
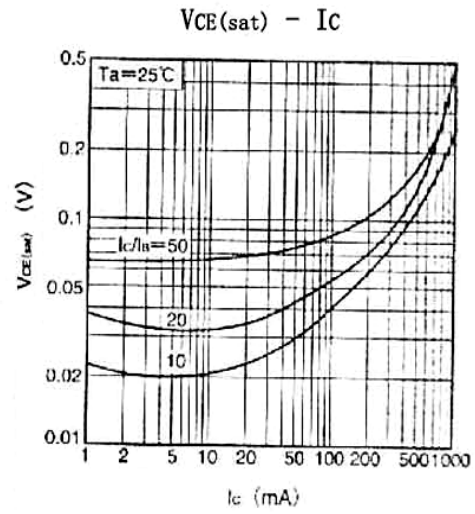
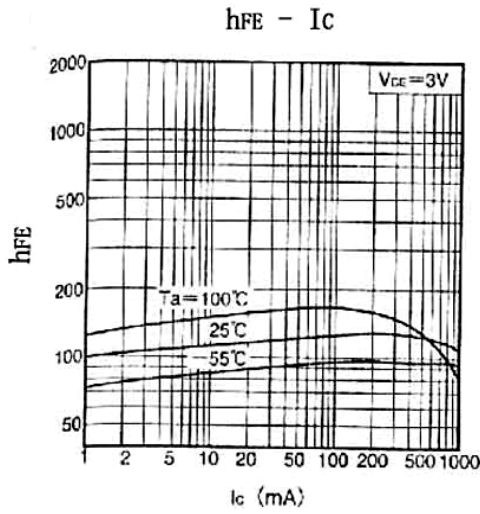
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	$V_{CBO}$	40	V
Collector to Emitter Voltage	$V_{CEO}$	32	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current-Continuous	$I_C$	1.0	A
Collector Base-Continuous(Pulse)	$I_{CP}$	2.0	A
Collector Power Dissipation	$P_C$	500	mW
Collector Power Dissipation	$P_C(T_c=25^\circ C)$	2.0	W
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=50\mu A$ $I_E=0$	40			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=1.0mA$ $I_B=0$	32			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=50\mu A$ $I_C=0$	5.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=20V$ $I_E=0$			0.5	$\mu A$
Emitter Base Cut-Off Current	$I_{EBO}$	$V_{EB}=4.0V$ $I_C=0$			0.5	$\mu A$
DC Current Gain	$h_{FE}$	$V_{CE}=3.0V$ $I_C=100mA$	82		390	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=500mA$ $I_B=50mA$		0.15	0.4	V
Transition Frequency	$f_T$	$V_{CE}=5.0V$ $f=100MHz$ $I_C=50mA$		150		MHz
Collector Output Capacitance	$C_{ob}$	$V_{CB}=10V$ $f=1.0MHz$ $I_E=0$		15		pF

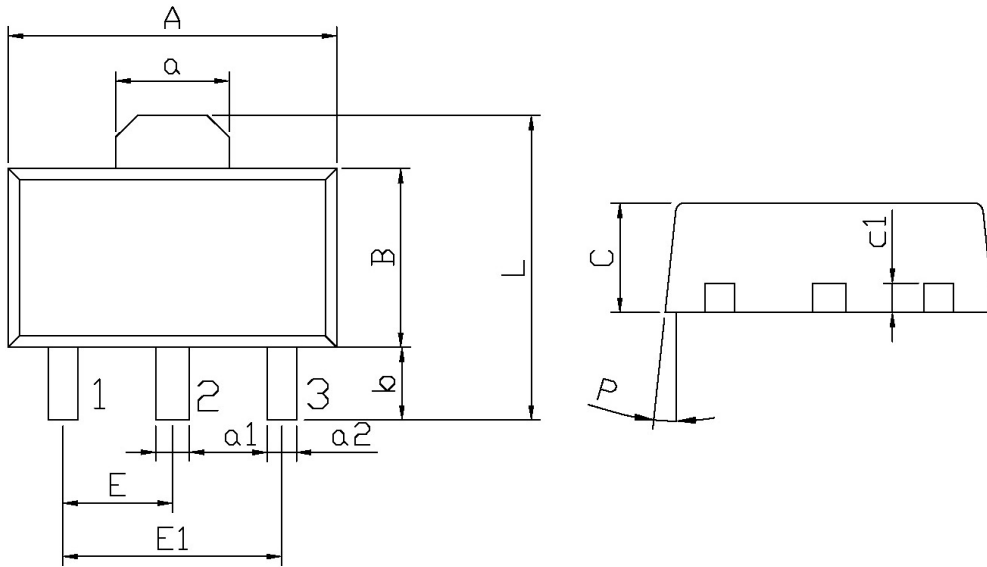
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

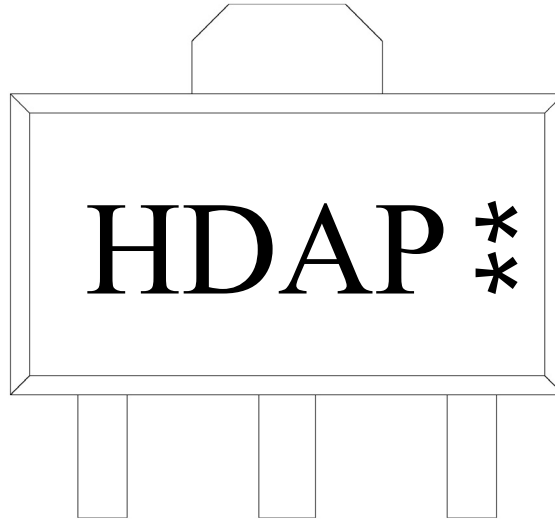
SOT-89

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.4	4.7	a1	0.36	0.56
B	2.35	2.65	a2	0.30	0.50
L	3.878	4.478	C	1.40	1.70
a	1.45	1.65	c1	0.35	0.50
E	1.40	1.60	P	6°	
E1	2.80	3.20			
b	0.80	1.20			

印章说明 / Marking Instructions



说明：

H： 为公司代码

DA： 为型号代码

P： 为 h<sub>FE</sub> 分档代码

\*\*： 为生产批号代码，随生产批号变化。

Note:

H: Company Code.

DA: Product Type.

P: h<sub>FE</sub> Classifications Symbol

\*\* : Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度  $25 \sim 150^\circ\text{C}$ ，时间  $60 \sim 90\text{sec}$ ;
- 2、峰值温度  $245 \pm 5^\circ\text{C}$ ，时间持续为  $5 \pm 0.5\text{sec}$ ;
- 3、焊接制程冷却速度为  $2 \sim 10^\circ\text{C}/\text{sec}$ .

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$ , Time: $60 \sim 90\text{sec}$ .
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$ , Duration: $5 \pm 0.5\text{sec}$ .
3. Cooling Speed:  $2 \sim 10^\circ\text{C}/\text{sec}$ .

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度： $260 \pm 5^\circ\text{C}$

时间： $10 \pm 1$  sec.

Temp.: $260 \pm 5^\circ\text{C}$

Time: $10 \pm 1$  sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-89	1,000	7	7,000	8	56,000	7" x12	180×120×180	385×257×392

**使用说明 / Notices**